

Spectrum Signal Wins Defense R&D Funds

Spectrum Signal Processing Inc. (Burnaby, B.C., www.spectrumsignal.com) is slated to receive over \$500,000 (Canadian) from the Defence Industrial Research Program (DIRP) to create additional capability for its flexComm line of software-defined radios. The DIRP, an initiative of Defence R&D Canada, funds defense-related industry re-

search and development. In this case, the money will go toward developing hardware and software that adds ultrawideband capability to Spectrum's SDRs. The ultrawideband SDRs, in turn, will serve as subsystems in a modem processing system for a software-configurable, military satellite communications terminal.

TI Embraces Linux for Its OMAP Platform

Texas Instruments, Inc. (Dallas; www.ti.com) has extended its OMAP wireless architecture to include the Linux operating system. The extension will give developers of Linux applications for 2.5G and 3G mobile devices easy access to the company's DSPs. In addition, TI has selected RidgeRun, Inc. (Boise, Idaho www.ridgerun.com), developer of the DSPLinux operating system, to directly assist its customers. It has also worked with RidgeRun to enhance DSPLinux to take advantage of the real-time multimedia capabilities of the OMAP platform.



TI Joins RapidIO Open-Standards Trade Group

Texas Instruments Incorporated (Dallas, www.ti.com) has joined the nonprofit, 50-plus-member RapidIO Trade Association (San Francisco; www.rapidio.org), an open-standards interconnect group that is pushing the use of "inside-the-box" high-performance switch fabric technology to multigigabit-per-second transmission rates. Toward that end, the association's RapidIO specification, released in March 2001, defines how chips and boards communicate within a system.



Duo Joins PCTEL Executive Team

PCTEL (Milpitas, Calif.; www.pctel.com) has named John Schoen and Jeff Miller to its executive team. Schoen will serve as both chief operating officer and chief financial officer, positions he held at SAFCO Technologies. Before that, he filled various financial spots during 19 years at Motorola. Miller, who will take over as vice president of development, led SAFCO's Test and Measurement Group for 3 years before it was acquired. Earlier, he led the implementation of the Cellnet cellular network and managed large software projects for Motorola's Cellular Infrastructure Group.



Dy 4 Taken by Force (Computers, That Is)

Dy 4 Systems (Kanata, Ont.; www.dy4.com) has been acquired by, and is now a business unit of, Force Computers (Fremont, Calif., www.forcecomputers.com). The acquisition is the result of a merger of Force's parent company, Solectron, and C-MAC Industries. Dy 4 will keep its brand of COTS ruggedized embedded computing products for the defense and aerospace industry. At the same time, it will draw on Force's hardware and software expertise in the commercial and telecom markets. For its part, Force aims to work Dy 4's DSP expertise into its OEM business.

Questra Caps Second Financing Round

Questra Corporation (Rochester, N.Y., www.questra.com) has completed a \$19 million second round of financing with Menlo Ventures and Trident Capital. Its enterprise software integrates mission-critical, intelligent devices with a company's service and support infrastructure via the Internet.



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